



Product Change Notification / RMES-19GFWK021

Date:

20-Jun-2022

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4663 Final Notice: Qualification of UAT as a new bumping site for SST25VF040B-50-4C-ZAE, SST25VF080B-50-4I-ZCE, SST25WF080BT-40I/CS and SST25WF080BT-40I/CS-GN catalog part numbers (CPN) available in 8L & 16L CSP and 9L WLCSP packages.

Affected CPNs:

[RMES-19GFWK021_Affected_CPN_06202022.pdf](#)
[RMES-19GFWK021_Affected_CPN_06202022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of UAT as a new bumping site for SST25VF040B-50-4C-ZAE, SST25VF080B-50-4I-ZCE, SST25WF080BT-40I/CS and SST25WF080BT-40I/CS-GN catalog part number (CPN) available in 8L & 16L CSP and 9L WLCSP packages.

Pre and Post Change Summary:

	Pre Change	Post Change
Bumping location	FlipChip International (FCI)	Unisem Advance Tech (UAT)
Backend Site	King Yuan Electronics Company, Limited (KYE)	King Yuan Electronics Company, Limited (KYE)
Solder Ball Material	SAC 305	SAC 405
Solder Ball Pitch	500 um	500 um
Solder Ball Size	300 um or 250 um	300 um or 250um
Polymer Thickness	4.5 um (P1 and P2)	7 um (P1 and P2)
UBM Deposition Method	Sputter	Sputter + plated
UBM Thickness	Al-NiV-Cu (0.4/0.345/0.835)um	0.1um Ti(sp.) + 0.2um Cu(sp.) + 8.6um Cu (pl.)
RDL Deposition method	Sputter	Sputter + plated
RDL Thickness	Ti-Al-Ti (0.1/1.8/0.1)um	0.1um Ti(sp.) + 0.2um Cu(sp.) + 4um Cu (pl.)

Impacts to Data Sheet: Slight modification to POD

Change ImpactNone

Reason for Change: To improve productivity by qualifying UAT as a new bumping site.

Change Implementation Status: In Progress

Estimated First Ship Date: July 18, 2022 (date code: 2230)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Date											
Qual Report Availability							X				
Final PCN Issue Date							X				
Estimated Implementation Date											X

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

December 19, 2021: Issued initial notification.

June 20, 2022: Issued final notification. Attached the qualification report. Updated the pre and post summary table to include backend site. Updated the impact to datasheet. Provided estimated first ship date to be on July 18, 2022.

Attachments:

[PCN_RMES-19GFWK021 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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